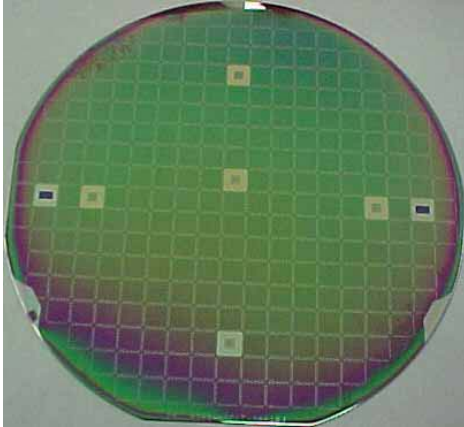
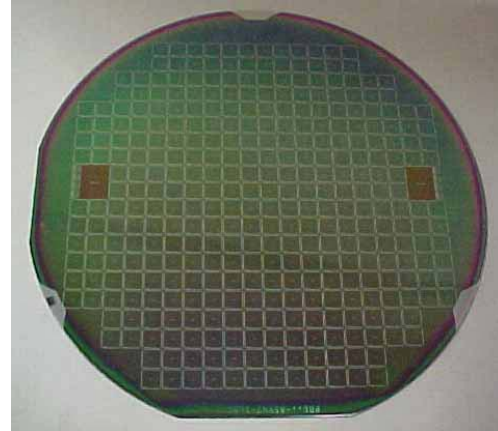


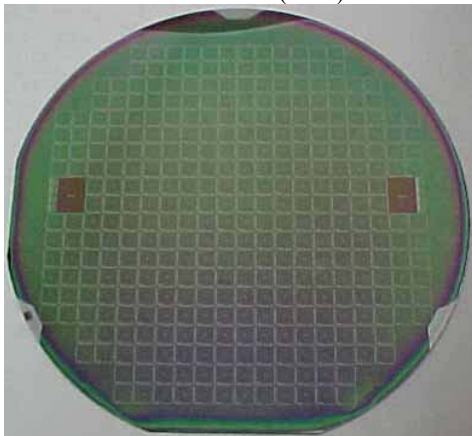
FCW48 – FCW96  
457um Pitch (18mil)



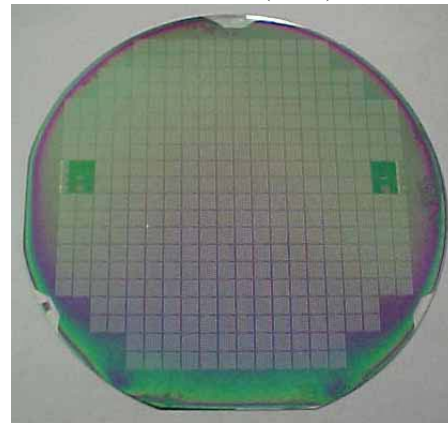
FCW88 – FCW176  
203um Pitch (8mil)



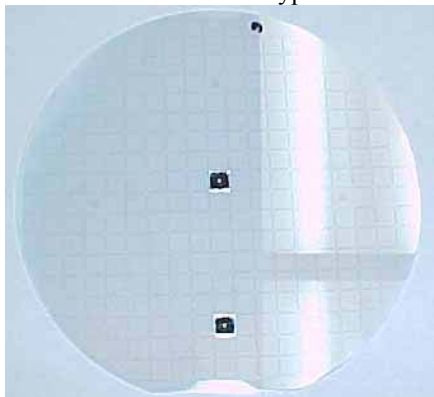
FCW112  
152um Pitch (6mil)



FCW317 – 1268 – 2853 - 5072  
254um Pitch (10mil)



FCQW Series  
Quartz Bumped Wafer  
Available all type



**General Specifications:**

**Metal Composition:**  
Al/Cu/Si (98/1/1)

**Die thickness:**  
24 mil (600~650μm)  
Thin die (back grinding) available.

**Metal Thickness:**  
8.9K Å (P=152μm)  
17K Å (P= 204~457μm)

**Passivation Thickness:**  
8K Å (Pitch 152~204μm)  
10K Å (Pitch 254~457μm)

**Passivation Type:**  
Nitride